

REMARKS

The present application has been amended in response to the Examiner's Office Action to place the application in condition for allowance. Applicant, by the amendments presented above, has made a concerted effort to present claims which clearly define over the prior art of record, and thus to place this case in condition for allowance.

In the Office Action, the Examiner rejected claims 1-10 under 35 U.S.C. § 102(b) as being anticipated by United States Patent No. 4,755,874 (Esrig et al.).

Each of the independent claims have been amended to further distinguish the present invention from that which is disclosed in Esrig et al. Specifically, claim 1 has been amended to claim the step of acquiring and collecting illumination and photoemission images for **each one of a plurality of die on the wafer**, as well as the step of overlaying, aligning, and assembling the collected images into a mosaic, **wherein spatial relationships between the plurality of die are maintained when forming the mosaic**. Claim 6 has been similarly amended, but is directed to a system. Applicant respectfully submits that this is not disclosed or suggested by the cited reference.

Esrig et al. discloses moving a module 23 so that an entire, **but single** DUT die is visible in the field of macro optics 30 and primary camera 13 (see col. 4, lines 51-54). Reflected, background, and emitted images are formed of the single die (see col. 4, lines 61-62). Then, the background image is subtracted from the emitted image, and the difference is superimposed on the reflected image to give a "global" composed image (see col. 5, lines 7-14). With this global

view, the operator can select possible bright spots in local area windows to zoom in for closer inspection with a higher magnification micro optics system (see col. 5, lines 18-22).

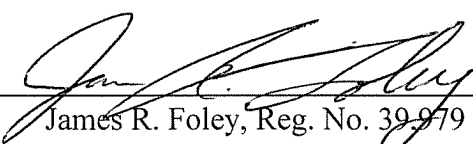
Esrig et al. does not disclose acquiring and collecting illumination and photoemission images for **each one of a plurality of die on a wafer**. Instead, Esrig et al. discloses collecting images of a **single die**. Esrig et al. also does not disclose **assembling the collected images into a mosaic, wherein spatial relationships between the plurality of die are maintained when forming the mosaic**. Instead, Esrig et al. discloses subtracting a background image of a single die from an emitted image, and superimposing the difference on a reflected image in order to provide a “global” composed image relating to that one die.

Applicant respectfully submits that Esrig et al. does not disclose what is now being specifically claimed in claims 1 and 6. As such, Applicant respectfully submits that claims 1 and 6, and those claims which depend therefrom, are allowable.

In view of the above amendments and remarks, Applicant respectfully submits that the claims of the application are allowable over the rejections of the Examiner. Should the present claims not be deemed adequate to effectively define the patentable subject matter, the Examiner is respectfully urged to call the undersigned attorney of record to discuss the claims in an effort to reach an agreement toward allowance of the present application.

Respectfully submitted,

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